



# SOT470-5

plastic, thermal enhanced low profile quad flat package; 100 leads; body 14 mm x 14 mm x 1.6 mm; exposed die pad

8 March 2017

Package information

## 1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package type industry code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	3-3-2017
Manufacturer package code	SOT470-5

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.9	-	14	14.1	mm
E	package width		13.9	-	14	14.1	mm
A	seated height		1.6	-	1.7	1.8	mm
A <sub>2</sub>	package height		1.55	-	1.6	1.65	mm
e	nominal pitch		-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	100	-	



2. Package outline

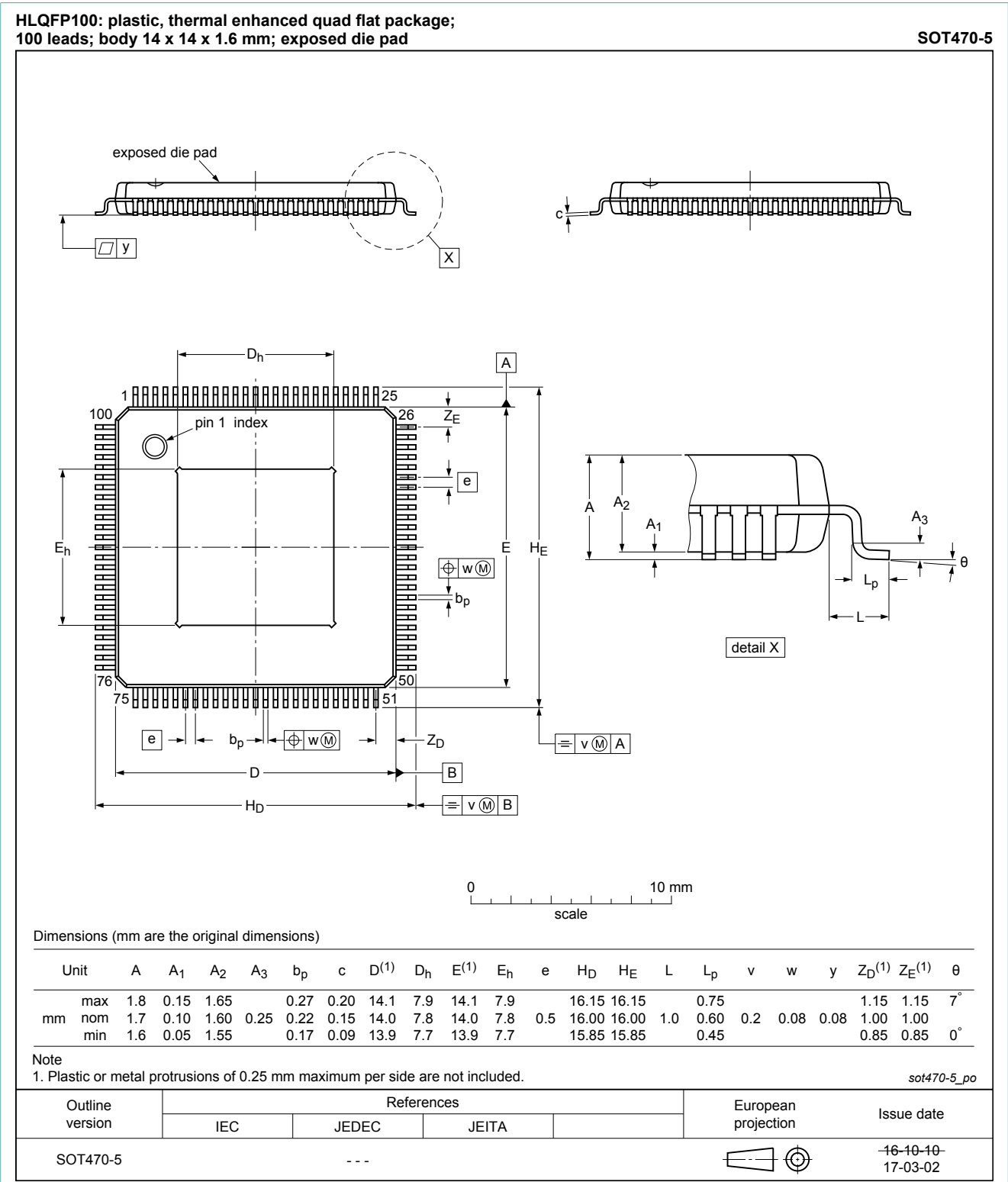


Fig. 1. Package outline HLQFP100 (SOT470-5)

3. Soldering

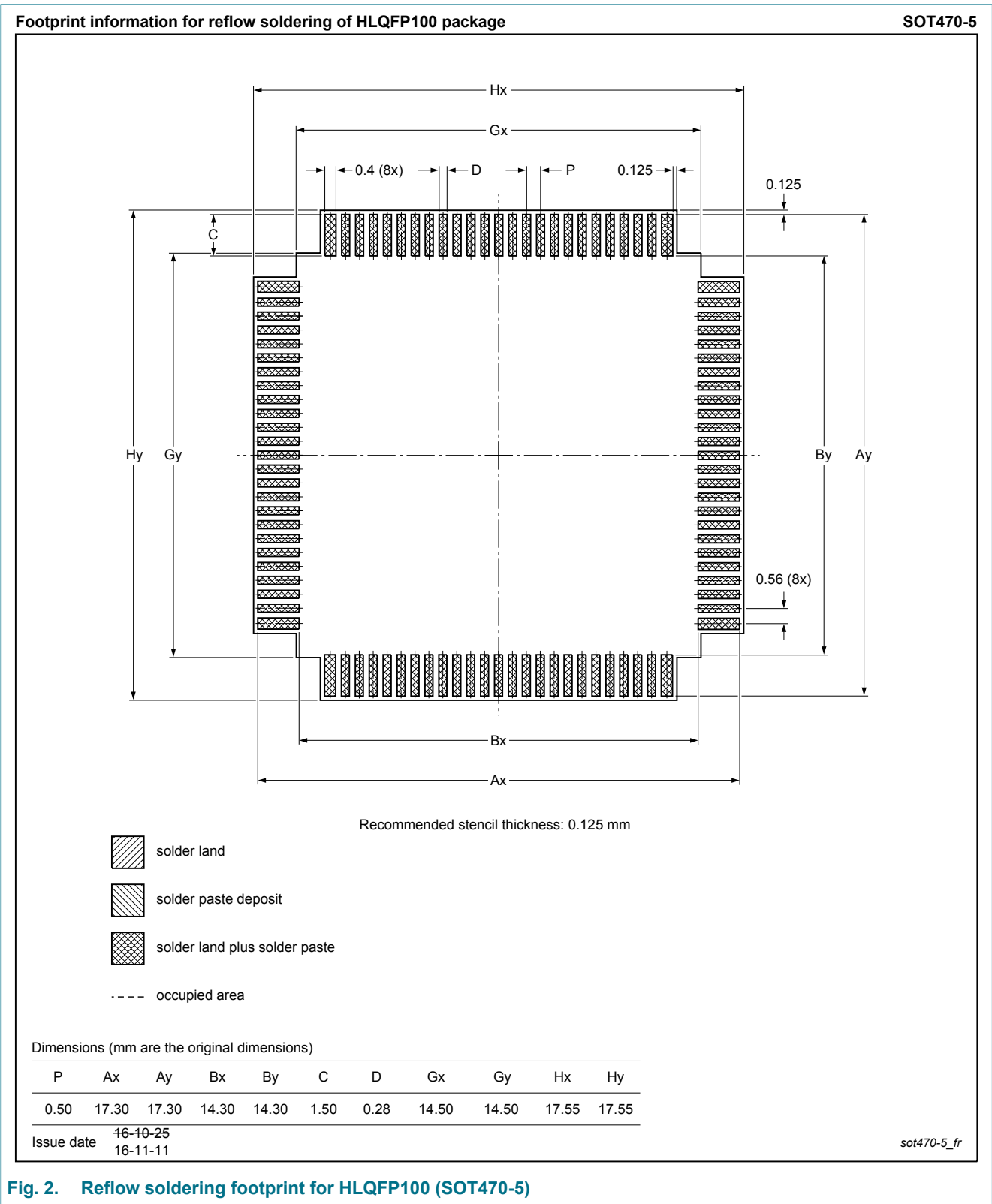


Fig. 2. Reflow soldering footprint for HLQFP100 (SOT470-5)

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## 4. Legal information

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